Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	439	(134/183).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:49
L2	49	US-3641973-\$.DID. OR US-3770598-\$. DID. OR US-3798056-\$.DID. OR US-3950184-\$.DID. OR US-3962047-\$. DID. OR US-3978578-\$.DID. OR US-4027686-\$.DID. OR US-4092176-\$. DID. OR US-4110176-\$.DID. OR US-4113492-\$.DID. OR US-4118303-\$. DID. OR US-4137867-\$.DID. OR US-4170959-\$.DID. OR US-4226208-\$. DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4280882-\$. DID. OR US-4304641-\$.DID. OR US-4315059-\$.DID. OR US-4336114-\$. DID. OR US-4339319-\$.DID. OR US-4341613-\$. DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:55
L3	135	"118"/\$.ccls. and polyvinylidene and fluoride	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 11:20
L4	111	"118"/\$.ccls. and (polyvinylidene near2 fluoride)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 11:22
L5	1	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (acid near3 resistant)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 11:23
L6	1	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (wafer near3 chuck)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 11:23
L7	50	semitool.asn. and (polyvinylidene near2 fluoride)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:23
L8	1	(semiconductor or wafer) and (process\$5 near10 chamber) and (polyvinylidene near2 fluoride) and (acid near3 retardant)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 11:24
L9	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/17 11:24

L10	0	L9 and (recircul)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L11	4	L9 and framework	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:24
L12	5	L9 and (processor near3 head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:24
L13	0	L9 and (dissipator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L14	0	L9 and (dissipater)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L15	0	L9 and ((heat near4 source) same platform)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53

L16	49	US-3641973-\$.DID. OR US-3770598-\$. DID. OR US-3798056-\$.DID. OR US-3950184-\$.DID. OR US-3962047-\$. DID. OR US-3978578-\$.DID. OR US-4027686-\$.DID. OR US-4092176-\$. DID. OR US-4110176-\$.DID. OR US-4113492-\$.DID. OR US-4118303-\$. DID. OR US-4137867-\$.DID. OR US-4170959-\$.DID. OR US-4226208-\$. DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4280882-\$. DID. OR US-4304641-\$.DID. OR US-4315059-\$.DID. OR US-4336114-\$. DID. OR US-4339319-\$.DID. OR US-4341613-\$. DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 11:24
L17	135	"118"/\$.ccls. and polyvinylidene and fluoride	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L18	111	"118"/\$.ccls. and (polyvinylidene near2 fluoride)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L19	1	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (acid near3 resistant)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L20	1	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (wafer near3 chuck)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L21	50	semitool.asn. and (polyvinylidene near2 fluoride)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L22	1506	(118/52).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	OFF	2006/04/17 10:54
			DERWENT; IBM_TDB			
L23	837	(118/302).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:26

L24	1713	(118/323).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:34
L25	88	(118/21).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:19
L26	151	(118/683).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:49
L27	298	(118/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:50
L28	1327	(118/300).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L29	584	(118/313).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L30	877	(118/315).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L31	994	(118/320).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53

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L32	1	(semiconductor or wafer) and (process\$5 near10 chamber) and (polyvinylidene near2 fluoride) and (acid near3 retardant)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L33	1518	(427/240).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L34	2947	(427/372.2).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L35	804	(427/421).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L36	0	(427/423).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L37	608	(427/425).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L38	155	(427/72).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L39	1595	(427/96).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53

L40	256	(438/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	OFF	2006/04/17 10:53
			DERWENT; IBM_TDB			-
L41	953	(438/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L42	586	(438/782).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L43	860	(134/33).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L44	370	(134/149).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L45	1178	(134/153).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L46	672	(134/157).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L47	2443	(134/902).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53

		1997			,	
L48	709	(134/182).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L49	1125	(134/200).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L50	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L51	0	L50 and (recircul)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L52	4	L50 and framework	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L53	5	L50 and (processor near3 head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L54	0	L50 and (dissipator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L55	0	L50 and (dissipater)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L56	0	L50 and ((heat near4 source) same platform)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53

L57	0	spray and (gas with condiuit) and (coating with conduit) and (metering with pump) and (viscosity with control)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L58	1	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (semiconductor same chuck)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L59	1	tokyo.asn. and electron.asn. and (recirculation) and (coating near10 solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L60	1	L9 and ((heat near4 chamber))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L61	1	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (semiconductor same chuck)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L62	1	tokyo.asn. and electron.asn. and (recirculation) and (coating near10 solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L63	1	L50 and ((heat near4 chamber))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L64	1	("5431421").PN.	USPAT	OR	OFF	2006/04/17 10:53

L65	25	US-3641973-\$.DID. OR US-3770598-\$. DID. OR US-3798056-\$.DID. OR US-3950184-\$.DID. OR US-3962047-\$. DID. OR US-3978578-\$.DID. OR US-4027686-\$.DID. OR US-4092176-\$. DID. OR US-4110176-\$.DID. OR US-4113492-\$.DID. OR US-4118303-\$. DID. OR US-4137867-\$.DID. OR US-4170959-\$.DID. OR US-4226208-\$. DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4280882-\$. DID. OR US-4304641-\$.DID. OR US-4315059-\$.DID. OR US-4336114-\$. DID. OR US-4339319-\$.DID. OR US-4341613-\$. DID. OR US-4351266-\$.DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID.	USPAT; USOCR	OR	ON	2006/04/17 10:53
L66	27	US-4376685-\$.DID. OR US-4405416-\$. DID. OR US-4428815-\$.DID. OR US-4435266-\$.DID. OR US-4466864-\$. DID. OR US-4469566-\$.DID. OR US-4489740-\$.DID. OR US-4510176-\$. DID. OR US-4514266-\$.DID. OR US-4518678-\$.DID. OR US-4534832-\$. DID. OR US-4565607-\$.DID. OR US-4597836-\$.DID. OR US-4624749-\$. DID. OR US-4675096-\$.DID. OR US-4693805-\$.DID. OR US-4696729-\$. DID. OR US-4732785-\$.DID. OR US-4750505-\$.DID. OR US-4827867-\$. DID. OR US-4828654-\$.DID. OR US-4838978-\$. DID. OR US-4838979-\$. DID. OR US-4856641-\$.DID. OR US-4861452-\$. DID. OR US-4856641-\$.DID. OR US-4861452-\$. DID. OR US-4861563-\$.DID. OR US-4861563-\$.DID.	USPAT; USOCR	OR	ON	2006/04/17 10:53
L67	27	US-4879007-\$.DID. OR US-4906346-\$. DID. OR US-4924890-\$.DID. OR US-4931149-\$.DID. OR US-5000827-\$. DID. OR US-5024746-\$.DID. OR US-5039381-\$.DID. OR US-5055425-\$. DID. OR US-5069760-\$.DID. OR US-5078852-\$.DID. OR US-5092975-\$. DID. OR US-5096550-\$.DID. OR US-5100502-\$.DID. OR US-5100516-\$. DID. OR US-5155336-\$.DID. OR US-5158100-\$.DID. OR US-5162260-\$. DID. OR US-5169408-\$.DID. OR US-522310-\$.DID. OR US-5224504-\$. DID. OR US-5228966-\$.DID. OR US-5230743-\$. DID. OR US-5238500-\$.DID. OR US-525807-\$.DID. OR US-5256274-\$. DID. OR US-5259407-\$.DID.	USPAT; USOCR	OR	ON	2006/04/17 10:53

L68	21	US-5275976-\$.DID. OR US-5290361-\$. DID. OR US-5294257-\$.DID. OR US-5312487-\$.DID. OR US-5316974-\$. DID. OR US-5328589-\$.DID. OR US-5232328-\$.DID. OR US-5332487-\$. DID. OR US-5235995-\$.DID. OR US-5252137-\$.DID. OR US-5270248-\$. DID. OR US-5340437-\$.DID. OR US-5349978-\$.DID. OR US-5368711-\$. DID. OR US-5372699-\$.DID. OR US-5377708-\$.DID. OR US-5391285-\$. DID. OR US-5415890-\$.DID. OR US-5421987-\$. DID. OR US-5429733-\$.DID.	USPAT; USOCR	OR	ON	2006/04/17 10:53
L69	2	("4651640").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L70	2	("4651440").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L71	2	("5156174").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L72	2	("4590094").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L73	10	("3136323"   "3494815"   "4027686"   "4161356"   "4745422"   "4788994"   "4871417"   "4922277").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L74	10	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (wafer near3 holder)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L75	11	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (semiconductor same holder)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L76	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/17 10:53

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L77	56	semitool and polyvinylidene	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L78	25	(semiconductor or wafer) and (process\$5 near10 chamber) and (polyvinylidene near2 fluoride) and (acid near3 resistant)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L79	9	(semiconductor or wafer) and ((process\$5 near10 chamber) same (acid near3 resistant))	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L80	2	(("4222345") or ("4282825")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/17 10:53
L81	2	tokyo.asn. and electron.asn. and (recirculating) and (coating near10 solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L82	6	tokyo.asn. and electron.asn. and (recycling) and (coating near10 solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L83	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L84	2	L9 and (recircul\$)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L85	5	L9 and ("250")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53

L86	25	US-3641973-\$.DID. OR US-3770598-\$. DID. OR US-3798056-\$.DID. OR US-3950184-\$.DID. OR US-3962047-\$. DID. OR US-3978578-\$.DID. OR US-4027686-\$.DID. OR US-4092176-\$. DID. OR US-4110176-\$.DID. OR US-4113492-\$.DID. OR US-4118303-\$. DID. OR US-4137867-\$.DID. OR US-4170959-\$.DID. OR US-4226208-\$. DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4280882-\$. DID. OR US-4304641-\$.DID. OR US-4315059-\$.DID. OR US-4336114-\$. DID. OR US-4339319-\$.DID. OR US-4341613-\$. DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID. OR US-4373988-\$.DID. OR	USPAT; USOCR	OR	ON	2006/04/17 10:53
L87	27	US-4376685-\$.DID. OR US-4405416-\$. DID. OR US-4428815-\$.DID. OR US-4435266-\$.DID. OR US-4466864-\$. DID. OR US-4469566-\$.DID. OR US-4489740-\$.DID. OR US-4510176-\$. DID. OR US-4514266-\$.DID. OR US-4518678-\$.DID. OR US-4534832-\$. DID. OR US-4565607-\$.DID. OR US-4597836-\$.DID. OR US-4624749-\$. DID. OR US-4675096-\$.DID. OR US-4693805-\$.DID. OR US-4696729-\$. DID. OR US-4732785-\$.DID. OR US-4750505-\$.DID. OR US-4827867-\$. DID. OR US-4828654-\$.DID. OR US-4838978-\$.DID. OR US-4838979-\$. DID. OR US-4856641-\$.DID. OR US-4856641-\$.DID. OR US-4861452-\$. DID. OR US-4861563-\$.DID. OR US-4861452-\$. DID. OR US-4861563-\$.DID. OR US-4861563-\$.DID.	USPAT; USOCR	OR	ON	2006/04/17 10:53
L88	27	US-4879007-\$.DID. OR US-4906346-\$. DID. OR US-4924890-\$.DID. OR US-4931149-\$.DID. OR US-5000827-\$. DID. OR US-5024746-\$.DID. OR US-5039381-\$.DID. OR US-5055425-\$. DID. OR US-5069760-\$.DID. OR US-5078852-\$.DID. OR US-5092975-\$. DID. OR US-5096550-\$.DID. OR US-5100502-\$.DID. OR US-5100516-\$. DID. OR US-5155336-\$.DID. OR US-5158100-\$.DID. OR US-5162260-\$. DID. OR US-5169408-\$.DID. OR US-522310-\$.DID. OR US-5224504-\$. DID. OR US-5227041-\$.DID. OR US-5230743-\$. DID. OR US-5238500-\$.DID. OR US-5256274-\$. DID. OR US-5259407-\$.DID.	USPAT; USOCR	OR	ON	2006/04/17 10:53

L89	21	US-5275976-\$.DID. OR US-5290361-\$.	USPAT;	OR	ON	2006/04/17 12:45
		DID. OR US-5294257-\$.DID. OR US-5312487-\$.DID. OR US-5316974-\$. DID. OR US-5328589-\$.DID. OR US-5232328-\$.DID. OR US-5332487-\$. DID. OR US-5235995-\$.DID. OR US-5252137-\$.DID. OR US-5270248-\$. DID. OR US-5340437-\$.DID. OR US-5349978-\$.DID. OR US-5368711-\$. DID. OR US-5372699-\$.DID. OR US-5377708-\$.DID. OR US-5391285-\$. DID. OR US-5405518-\$.DID. OR US-5415890-\$.DID. OR US-5421987-\$. DID. OR US-5429733-\$.DID.	USOCR			
L90	2	("4651640").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L91	2	("4651440").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L92	2	("5156174").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L93	2	("4590094").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L94	10	("3136323"   "3494815"   "4027686"   "4161356"   "4745422"   "4788994"   "4871417"   "4922277").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L95	10	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (wafer near3 holder)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L96	11	"118"/\$.ccls. and (polyvinylidene near2 fluoride) and (semiconductor same holder)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L97	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/17 10:53

			LIC DODUD		T 011	2005/04/47 40 70
L98	56	semitool and polyvinylidene	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L99	25	(semiconductor or wafer) and (process\$5 near10 chamber) and (polyvinylidene near2 fluoride) and (acid near3 resistant)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L100	9	(semiconductor or wafer) and ((process\$5 near10 chamber) same (acid near3 resistant))	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L101	2	(("4222345") or ("4282825")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/17 10:53
L102	2	tokyo.asn. and electron.asn. and (recirculating) and (coating near10 solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L103	6	tokyo.asn. and electron.asn. and (recycling) and (coating near10 solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L104	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L105	2	L50 and (recircul\$)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L106	5	L50 and ("250")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L107	9	(("5235995") or ("5238500") or ("5168886") or ("5168887") or ("5085560")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53

		40				
L108	5	(("5235995") or ("5238500") or ("5168886") or ("5168887") or ("5085560")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L109	4	(("5238500") or ("5168886") or ("5168887") or ("5085560")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L110	4	(("6375741") or ("5658387") or ("5321421") or ("5235995")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L111	19	(("5,238,500") or ("5,232,511") or ("5, 370,741") or ("5,500,081") or ("5,357, 991") or ("5,168,886") or ("5,230, 743") or ("5,224,504") or ("5,168, 887") or ("5,156,174") or ("5,222, 310") or ("5,445,172") or ("5,573, 023") or ("5,377,708") or ("6,066, 575") or ("5,658,387") or ("6,375, 741") or ("5,431,421") or ("5,235, 995")).PN.	USPAT	OR	OFF	2006/04/17 10:53
L112	297	tokyo.asn. and electron.asn. and (heat near4 chamber) and heater	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 10:53
L113	1148	(118/503).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 10:53
L114	13	("3993018"   "4677758"   "4744713"   "4817556"   "4971676"   "5040484"). PN. OR ("5350427").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L115	48	("3585668"   "4313266"   "4651440"   "4687542"   "4745422"   "4788994"). PN. OR ("5431421").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L116	18	("4118303"   "4165252"   "4473455"   "5078852"   "5230741"   "5276976"   "5326725"   "5377708"   "5405518"   "5429733"   "5431421"   "5437777"   "5605574"   "5605866"   "5620581"   "5762751"   "5985126"   "6322678"). PN. OR ("6849167").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 10:53
L117	1	("5,415,578").PN.	USPAT	OR	OFF	2006/04/17 10:53
L118	2456	(118/500).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:00

L119	310	(269/46).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/17 11:19
L120	0	wafer.clm. and processing.clm. and bowl.clm. and chemical.clm. and supply.clm. and (overlay.clm. or periphery.clm.)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 12:46
L121	0	wafer.clm. and bowl.clm. and chemical.clm. and supply.clm. and (overlay.clm.)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 12:46
L122	0	wafer.clm. and bowl.clm. and chemical.clm. and supply.clm. and (overlay.clm. or peripherally.clm.)	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/17 12:46
S20 4	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/05 12:00
S24 9	6	(("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741")).PN.	USPAT	OR	OFF	2006/04/05 12:00

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